Zilog - Z86E0412HSG1866 Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	Z8
Core Size	8-Bit
Speed	12MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	14
Program Memory Size	1KB (1K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	125 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z86e0412hsg1866

GENERAL DESCRIPTION (Continued)

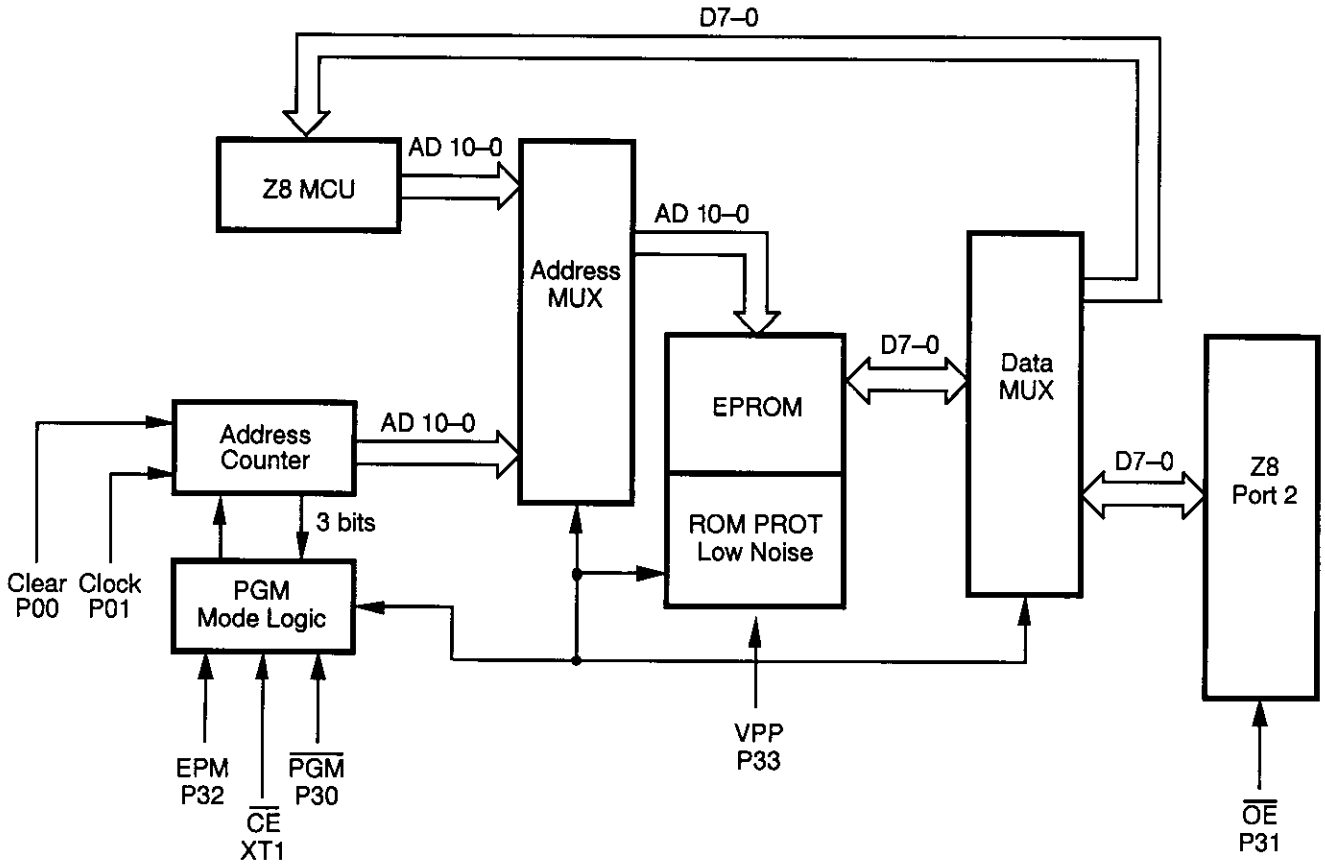


Figure 2. EPROM Programming Mode Block Diagram

PIN DESCRIPTION

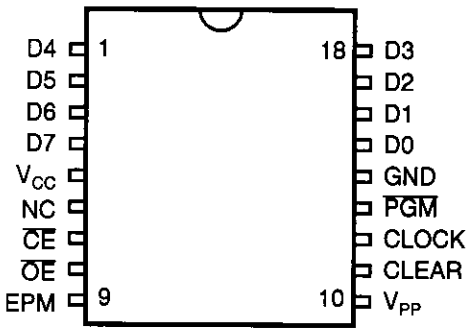


Figure 3. 18-Pin EPROM Mode Configuration

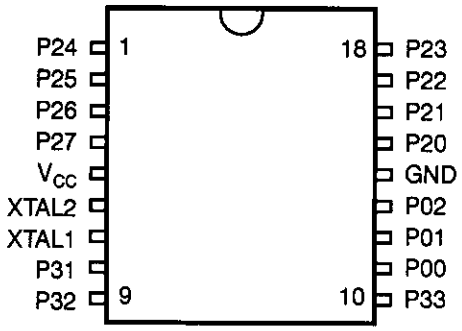


Figure 4. 18-Pin DIP/SOIC Mode Configuration

Table 1. 18-Pin DIP Pin Identification

EPROM Programming Mode			
Pin #	**Symbol**	**Function**	**Direction**
1–4	D4–D7	Data 4, 5, 6, 7	In/Output
5	V_{CC}	Power Supply	
6	NC	No Connection	
7	$\overline{CE}$	Chip Enable	Input
8	$\overline{OE}$	Output Enable	Input
9	EPM	EPROM Prog Mode	Input
10	V_{PP}	Prog Voltage	Input
11	Clear	Clear Clock	Input
12	Clock	Address	Input
13	$\overline{PGM}$	Prog Mode	Input
14	GND	Ground	
15–18	D0–D3	Data 0,1, 2, 3	In/Output

Table 2. 18-Pin DIP/SOIC Pin Identification

Standard Mode			
Pin #	**Symbol**	**Function**	**Direction**
1–4	P24–P27	Port 2, Pins 4,5,6,7	In/Output
5	V_{CC}	Power Supply	
6	XTAL2	Crystal Osc. Clock	Output
7	XTAL1	Crystal Osc. Clock	Input
8	P31	Port 3, Pin 1, AN1	Input
9	P32	Port 3, Pin 2, AN2	Input
10	P33	Port 3, Pin 3, REF	Input
11–13	P00–P02	Port 0, Pins 0,1,2	In/Output
14	GND	Ground	
15–18	P20–P23	Port 2, Pins 0,1,2,3	In/Output

ABSOLUTE MAXIMUM RATINGS

Stresses greater than those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at any condition above those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for an extended period may affect device reliability. Total power dissipation should not exceed 462 mW for the package. Power dissipation is calculated as follows:

Total Power Dissipation = V_{DD} x [I_{DD}–(sum of I_{OH})]
+ sum of [(V_{DD}–V_{OH}) x I_{OH}]
+ sum of (V_{OL} x I_{OL})

Parameter	Min	Max	Units	Note
Ambient Temperature under Bias	–40	+105	C	
Storage Temperature	–65	+150	C	
Voltage on any Pin with Respect to V_{SS}	–0.7	+12	V	1
Voltage on V_{DD} Pin with Respect to V_{SS}	–0.3	+7	V	
Voltage on Pins 7, 8, 9, 10 with Respect to V_{SS}	–0.6	V_{DD}+1	V	2
Total Power Dissipation		1.65	W	
Maximum Allowable Current out of V_{SS}		300	mA	
Maximum Allowable Current into V_{DD}		220	mA	
Maximum Allowable Current into an Input Pin	–600	+600	µA	3
Maximum Allowable Current into an Open-Drain Pin	–600	+600	µA	4
Maximum Allowable Output Current Sinked by Any I/O Pin		25	mA	
Maximum Allowable Output Current Sourced by Any I/O Pin		25	mA	
Total Maximum Output Current Sinked by a Port		60	mA	
Total Maximum Output Current Sourced by a Port		45	mA	

Notes:

1. This applies to all pins except where otherwise noted. Maximum current into pin must be ± 600 µA.
2. There is no input protection diode from pin to V_{DD} (not applicable to EPROM Mode).
3. This excludes Pin 6 and Pin 7.
4. Device pin is not at an output Low state.

STANDARD TEST CONDITIONS

The characteristics listed below apply for standard test conditions as noted. All voltages are referenced to Ground. Positive current flows into the referenced pin (Figure 5).

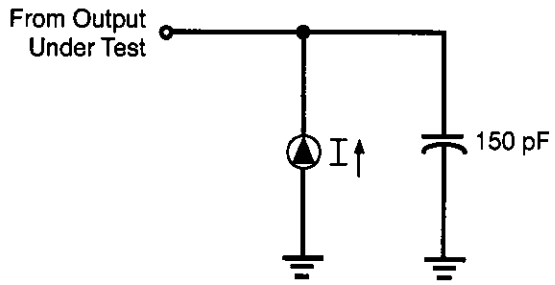


Figure 5. Test Load Diagram

CAPACITANCE

T_A = 25°C, V_{CC} = GND = 0V, f = 1.0 MHz, unmeasured pins returned to GND.

Parameter	Min	Max
Input capacitance	0	10 pF
Output capacitance	0	20 pF
I/O capacitance	0	25 pF

DC ELECTRICAL CHARACTERISTICS (Continued)

Sym	Parameter	V_{CC} [4]	T_A = 0°C to +70°C Min	Max	Typical @ 25°C	Units	Conditions	Notes
I_{CC1}	Standby Current (Low Noise Mode)	4.5V		4.0	2.5	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 1 MHz	7
		5.5V		4.0	2.5	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 1 MHz	7
		4.5V		4.5	2.8	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 2 MHz	7
		5.5V		4.5	2.8	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 2 MHz	7
		4.5V		5.0	3.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 4 MHz	7
		5.5V		5.0	3.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 4 MHz	7
I_{CC2}	Standby Current	4.5V		10.0	1.0	µA	STOP Mode V_{IN} = 0V, V_{CC} WDT is not Running	7,8
		5.5V		10.0	1.0	µA	STOP Mode V_{IN} = 0V,V_{CC} WDT is not Running	7,8
I_{ALL}	Auto Latch Low Current	4.5V		32.0	16	µA	$0V < V_{IN} < V_{CC}$	
		5.5V		32.0	16	µA	$0V < V_{IN} < V_{CC}$	
I_{ALH}	Auto Latch High Current	4.5V		–16.0	–8.0	µA	$0V < V_{IN} < V_{CC}$	
		5.5V		–16.0	–8.0	µA	$0V < V_{IN} < V_{CC}$	

Notes:

1. Port 2 and Port 0 only
2. V_{SS} = 0V = GND
3. The device operates down to V_{LV} of the specified frequency for V_{LV}. The minimum operational V_{CC} is determined on the value of the voltage V_{LV} at the ambient temperature. The V_{LV} increases as the temperature decreases.
4. V_{CC} = 4.5 to 5.5V, typical values measured at V_{CC} = 5.0V.
   The V_{CC} voltage specification of 5.5 V guarantees 5.0 V ± 0.5V with typical values measured at V_{CC} = 5.0V.
5. Standard Mode (not Low EMI Mode)
6. Z86E08 only
7. All outputs unloaded and all inputs are at V_{CC} or V_{SS} level.
8. If analog comparator is selected, then the comparator inputs must be at V_{CC} level.

DC ELECTRICAL CHARACTERISTICS

Extended Temperature

Sym	Parameter	V_{CC} [4]	T_A = –40°C to +105°C Min	Max	Typical @ 25°C	Units	Conditions	Notes
V_{INMAX}	Max Input Voltage	4.5V		12.0		V	I_{IN} < 250 µA	1
		5.5V		12.0		V	I_{IN} < 250 µA	1
V_{CH}	Clock Input High Voltage	4.5V	0.8 V_{CC}	V_{CC}+0.3	2.8	V	Driven by External Clock Generator	
		5.5V	0.8 V_{CC}	V_{CC}+0.3	2.8	V	Driven by External Clock Generator	
V_{CL}	Clock Input Low Voltage	4.5V	V_{SS}–0.3	0.2 V_{CC}	1.7	V	Driven by External Clock Generator	
		5.5V	V_{SS}–0.3	0.2 V_{CC}	1.7	V	Driven by External Clock Generator	
V_{IH}	Input High Voltage	4.5V	0.7 V_{CC}	V_{CC}+0.3	2.8	V		
		5.5V	0.7 V_{CC}	V_{CC}+0.3	2.8	V		
V_{IL}	Input Low Voltage	4.5V	V_{SS}–0.3	0.2 V_{CC}	1.5	V		
		5.5V	V_{SS}–0.3	0.2 V_{CC}	1.5	V		
V_{OH}	Output High Voltage	4.5V	V_{CC}–0.4		4.8	V	I_{OH} = –2.0 mA	5
		5.5V	V_{CC}–0.4		4.8	V	I_{OH} = –2.0 mA	5
		4.5V	V_{CC}–0.4			V	Low Noise @ I_{OH} = –0.5 mA	
		5.5V	V_{CC}–0.4			V	Low Noise @ I_{OH} = –0.5 mA	
V_{OL1}	Output Low Voltage	4.5V		0.4	0.1	V	I_{OL} = +4.0 mA	5
		5.5V		0.4	0.1	V	I_{OL} = +4.0 mA	5
		4.5V		0.4	0.1	V	Low Noise @ I_{OL} = 1.0 mA	
		5.5V		0.4	0.1	V	Low Noise @ I_{OL} = 1.0 mA	
V_{OL2}	Output Low Voltage	4.5V		1.0	0.3	V	I_{OL} = +12 mA,	5
		5.5V		1.0	0.3	V	I_{OL} = +12 mA,	5
V_{OFFSET}	Comparator Input Offset Voltage	4.5V		25.0	10.0	mV		
		5.5V		25.0	10.0	mV		
V_{LV}	V_{CC} Low Voltage Auto Reset		1.8	3.8	2.8	V	@ 6 MHz Max. Int. CLK Freq.	3
I_{IL}	Input Leakage (Input Bias Current of Comparator)	4.5V		–1.0	1.0	µA	V_{IN} = 0V, V_{CC}	
		5.5V		–1.0	1.0	µA	V_{IN} = 0V, V_{CC}	
I_{OL}	Output Leakage	4.5V		–1.0	1.0	µA	V_{IN} = 0V, V_{CC}	
		5.5V		–1.0	1.0	µA	V_{IN} = 0V, V_{CC}	
V_{ICR}	Comparator Input Common Mode Voltage Range		0	V_{CC} –1.5		V		

DC ELECTRICAL CHARACTERISTICS (Continued)

Sym	Parameter	V_{CC} [4]	T_A = –40°C to +105°C Min	Max	Typical @ 25°C	Units	Conditions	Notes
I_{CC}	Supply Current	4.5V		11.0	6.8	mA	All Output and I/O Pins Floating @ 2 MHz	5,7
		5.5V		11.0	6.8	mA	All Output and I/O Pins Floating @ 2 MHz	5,7
		4.5V		15.0	8.2	mA	All Output and I/O Pins Floating @ 8 MHz	5,7
		5.5V		15.0	8.2	mA	All Output and I/O Pins Floating @ 8 MHz	5,7
		4.5V		20.0	12.0	mA	All Output and I/O Pins Floating @ 12 MHz	5,7
		5.5V		20.0	12.0	mA	All Output and I/O Pins Floating @ 12 MHz	5,7
I_{CC1}	Standby Current	4.5V		5.0	2.5	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 2 MHz	5,7
		5.5V		5.0	2.5	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 2 MHz	5,7
		4.5V		5.0	3.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 8 MHz	5,7
		5.5V		5.0	3.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 8 MHz	5,7
		4.5V		7.0	4.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 12 MHz	5,7
		5.5V		7.0	4.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 12 MHz	5,7
I_{CC}	Supply Current (Low Noise Mode)	4.5V		11.0	6.8	mA	All Output and I/O Pins Floating @ 1 MHz	7
		5.5V		11.0	6.8	mA	All Output and I/O Pins Floating @ 1 MHz	7
		4.5V		13.0	7.5	mA	All Output and I/O Pins Floating @ 2 MHz	7
		5.5V		13.0	7.5	mA	All Output and I/O Pins Floating @ 2 MHz	7
		4.5V		15.0	8.2	mA	All Output and I/O Pins Floating @ 4 MHz	7
		5.5V		15.0	8.2	mA	All Output and I/O Pins Floating @ 4 MHz	7

Sym	Parameter	V_{CC} [4]	T_A = –40°C to +105°C Min	Max	Typical @ 25°C	Units	Conditions	Notes
I_{CC1}	Standby Current (Low Noise Mode)	4.5V		4.0	2.5	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 1 MHz	7
		5.5V		4.0	2.5	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 1 MHz	7
		4.5V		4.5	2.8	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 2 MHz	7
		5.5V		4.5	2.8	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 2 MHz	7
		4.5V		5.0	3.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 4 MHz	7
		5.5V		5.0	3.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 4 MHz	7
I_{CC2}	Standby Current	4.5V		20	1.0	µA	STOP Mode V_{IN} = 0V, V_{CC} WDT is not Running	7,8
		5.5V		20	1.0	µA	STOP Mode V_{IN} = 0V, V_{CC} WDT is not Running	7,8
I_{ALL}	Auto Latch Low Current	4.5V		40	16	µA	$0V < V_{IN} < V_{CC}$	
		5.5V		40	16	µA	$0V < V_{IN} < V_{CC}$	
I_{ALH}	Auto Latch High Current	4.5V		–20.0	–8.0	µA	$0V < V_{IN} < V_{CC}$	
		5.5V		–20.0	–8.0	µA	$0V < V_{IN} < V_{CC}$	

Notes:

1. Port 2 and Port 0 only
2. V_{SS} = 0V = GND
3. The device operates down to V_{LV} of the specified frequency for V_{LV}. The minimum operational V_{CC} is determined on the value of the voltage V_{LV} at the ambient temperature. The V_{LV} increases as the temperature decreases.
4. V_{CC} = 4.5V to 5.5V, typical values measured at V_{CC} = 5.0V
5. Standard Mode (not Low EMI Mode)
6. Z86E08 only
7. All outputs unloaded and all inputs are at V_{CC} or V_{SS} level.
8. If analog comparator is selected, then the comparator inputs must be at V_{CC} level.

AC ELECTRICAL CHARACTERISTICS (Continued)

Low Noise Mode, Extended Temperature

				T_A= –40 °C to +105 °C					
				1 MHz		4 MHz			
No	Symbol	Parameter	V_{CC}	Min	Max	Min	Max	Units	Notes
1	TPC	Input Clock Period	4.5V	1000	DC	250	DC	ns	1
			5.5V	1000	DC	250	DC	ns	1
2	TrC TfC	Clock Input Rise and Fall Times	4.5V		25		25	ns	1
			5.5V		25		25	ns	1
3	TwC	Input Clock Width	4.5V	500		125		ns	1
			5.5V	500		125		ns	1
4.	TwTinL	Timer Input Low Width	4.5V	70		70		ns	1
			5.5V	70		70		ns	1
5	TwTinH	Timer Input High Width	4.5V	2.5TpC		2.5TpC			1
			5.5V	2.5TpC		2.5TpC			1
6	TpTin	Timer Input Period	4.5V		4TpC	4TpC			1
			5.5V		4TpC	4TpC			1
7	TrTin, TtTin	Timer Input Rise and Fall Time	4.5V		100		100	ns	1
			5.5V		100		100	ns	1
8	TwIL	Int. Request Input Low Time	4.5V	70		70		ns	1,2
			5.5V	70		70		ns	1,2
9	TwIH	Int. Request Input High Time	4.5V	2.5TpC		2.5TpC			1,2
			5.5V	2.5TpC		2.5TpC			1,2
10	Twdt	Watch-Dog Timer Delay Time for Timeout	4.5V	10		10		ms	1
			5.5V	10		10		ms	1

Notes:

1. Timing Reference uses 0.7 V_{CC} for a logic 1 and 0.2 V_{CC} for a logic 0.
2. Interrupt request through Port 3 (P33–P31).

PIN FUNCTIONS (Continued)

XTAL1, XTAL2 *Crystal In, Crystal Out* (time-based input and output, respectively). These pins connect a parallel-resonant crystal, LC, or an external single-phase clock (8 MHz or 12 MHz max) to the on-chip clock oscillator and buffer.

Port 0, P02–P00. Port 0 is a 3-bit bidirectional, Schmitt-triggered CMOS-compatible I/O port. These three I/O lines can be globally configured under software control to be inputs or outputs (Figure 7).

Auto Latch. The Auto Latch puts valid CMOS levels on all CMOS inputs (except P33, P32, P31) that are not externally driven. A valid CMOS level, rather than a floating node, reduces excessive supply current flow in the input buffer. On Power-up and Reset, the Auto Latch will set the ports to an undetermined state of 0 or 1. Default condition is Auto Latches enabled.

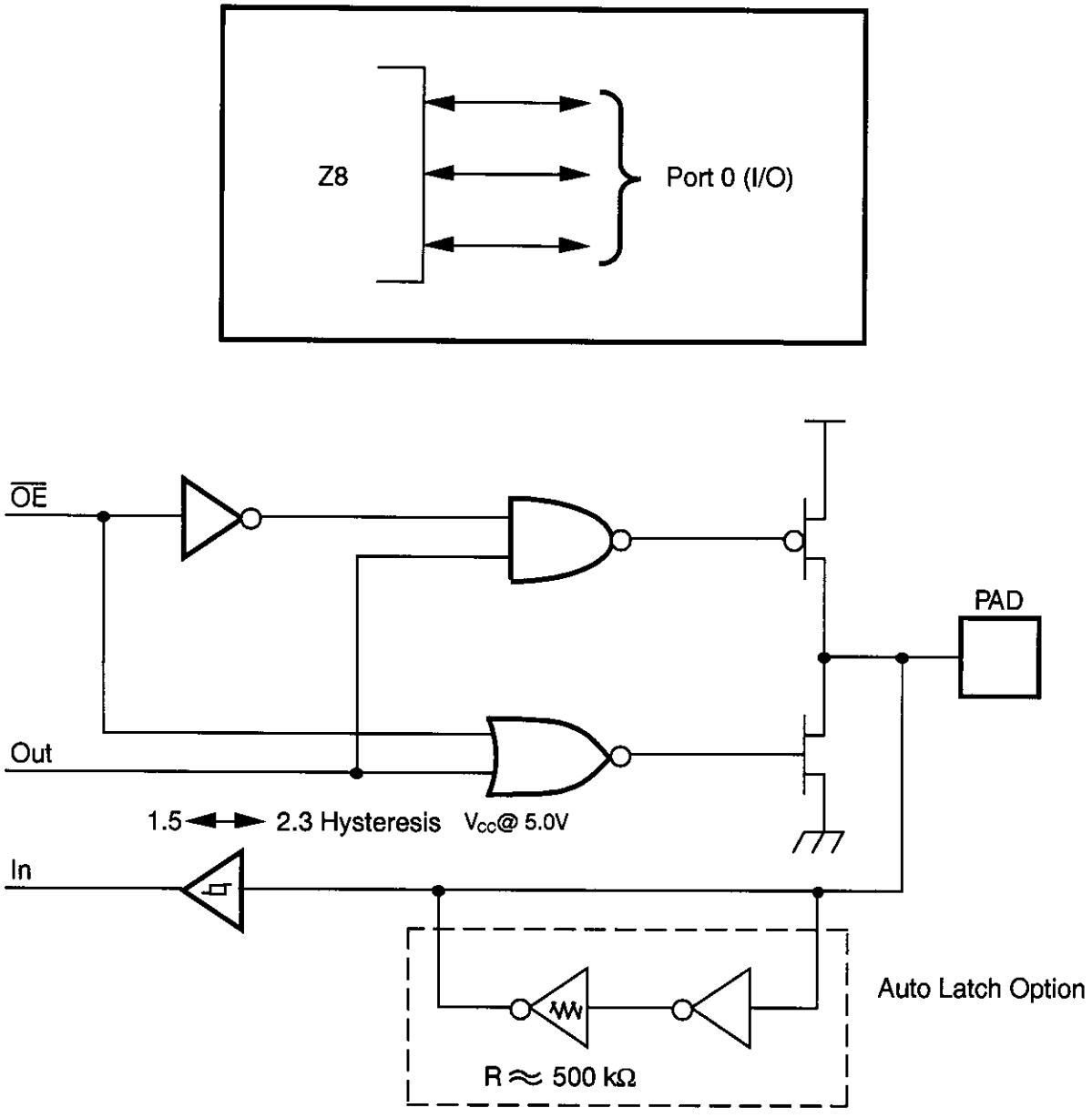


Figure 7. Port 0 Configuration

PIN FUNCTIONS (Continued)

Port 3, P33–P31. Port 3 is a 3-bit, CMOS-compatible port with three fixed input (P33–P31) lines. These three input lines can be configured under software control as digital Schmitt-trigger inputs or analog inputs. These three input lines are also used as the interrupt sources IRQ0–IRQ3, and as the timer input signal T_{IN} (Figure 9).

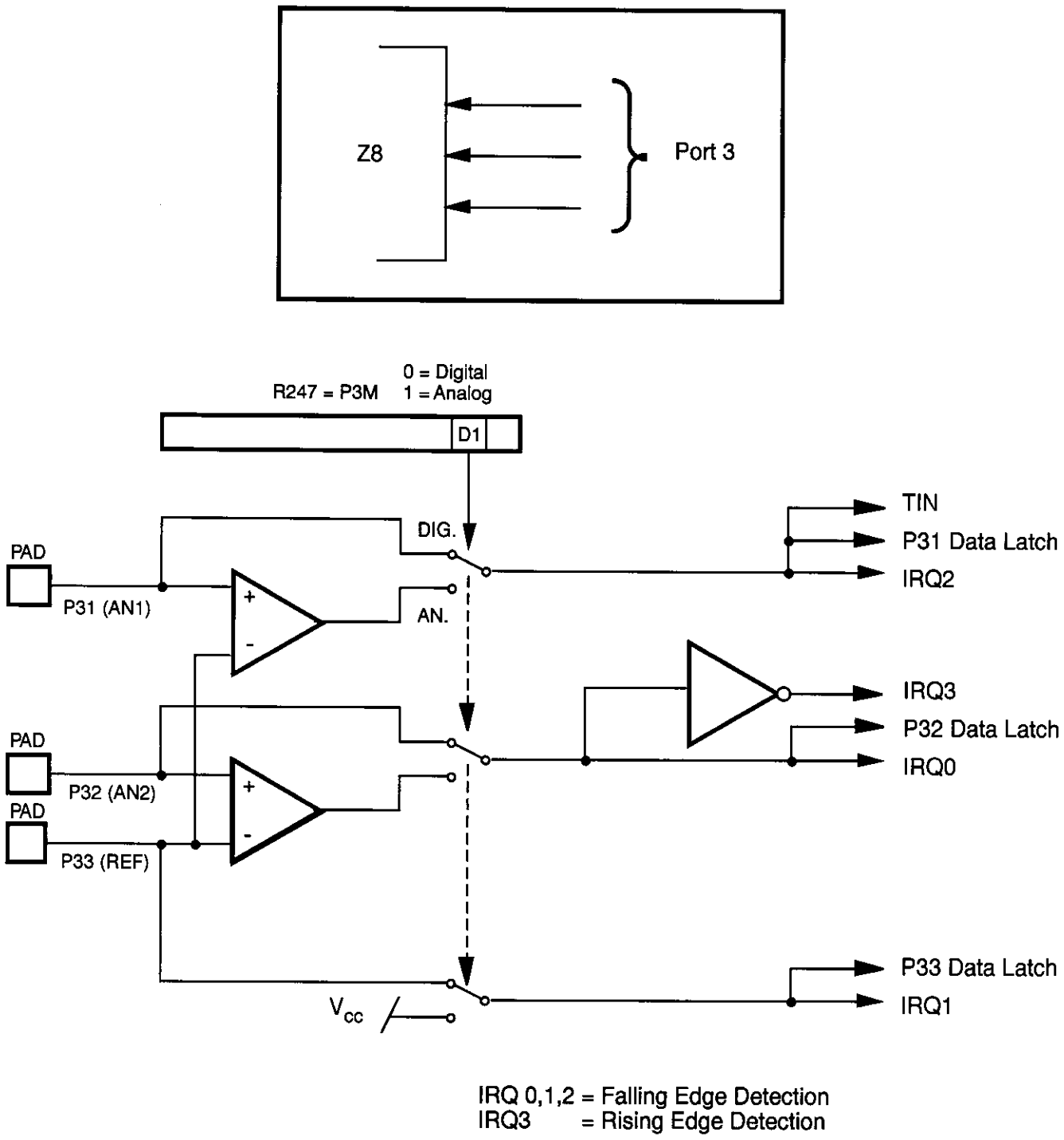


Figure 9. Port 3 Configuration

FUNCTIONAL DESCRIPTION (Continued)

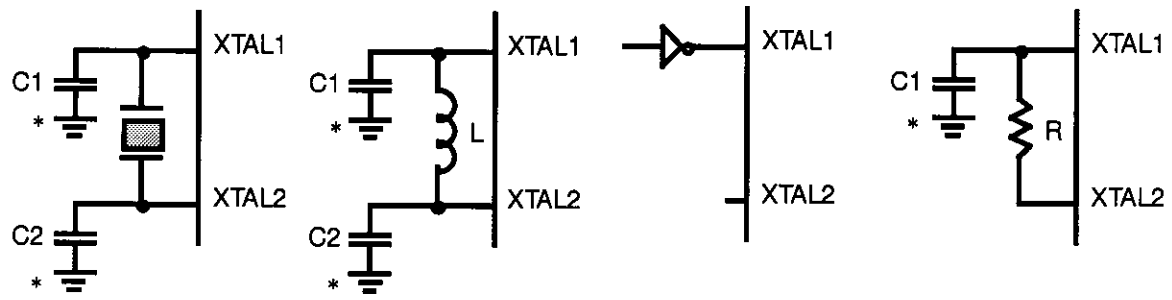
Table 3. Control Registers

		Reset Condition								
Addr.	**Reg.**	**D7**	**D6**	**D5**	**D4**	**D3**	**D2**	**D1**	**D0**	**Comments**
FF	SPL	0	0	0	0	0	0	0	0	
FD	RP	0	0	0	0	0	0	0	0	
FC	FLAGS	U	U	U	U	U	U	U	U	
FB	IMR	0	U	U	U	U	U	U	U	
FA	IRQ	U	U	0	0	0	0	0	0	IRQ3 is used for positive edge detection
F9	IPR	U	U	U	U	U	U	U	U	
F8*	P01M	U	U	U	0	U	U	0	1	
F7*	P3M	U	U	U	U	U	U	0	0	
F6*	P2M	1	1	1	1	1	1	1	1	Inputs after reset
F5	PRE0	U	U	U	U	U	U	U	0	
F4	T0	U	U	U	U	U	U	U	U	
F3	PRE1	U	U	U	U	U	U	0	0	
F2	T1	U	U	U	U	U	U	U	U	
F1	TMR	0	0	0	0	0	0	0	0	

Note: *Registers are not reset after a STOP-Mode Recovery using P27 pin. A subsequent reset will cause these control registers to be reconfigured as shown in Table 4 and the user must avoid bus contention on the port pins or it may affect device reliability.

Clock. The Z8 on-chip oscillator has a high-gain, parallel-resonant amplifier for connection to a crystal, LC, RC, ceramic resonator, or any suitable external clock source (XTAL1 = INPUT, XTAL2 = OUTPUT). The crystal should be AT cut, up to 12 MHz max., with a series resistance (RS) of less than or equal to 100 Ohms.

The crystal should be connected across XTAL1 and XTAL2 using the vendors crystal recommended capacitors from each pin directly to device ground pin 14 (Figure 16). Note that the crystal capacitor loads should be connected to V_{SS}, Pin 14 to reduce Ground noise injection.



Ceramic Resonator or Crystal
C1, C2 = 47 pF TYP *
F = 8 MHz

LC

External Clock

RC
@ 5V Vcc (TYP)

C1 = 100 pF
R = 2K
F = 6 MHz

* Typical value including pin parasitics

Figure 16. Oscillator Configuration

FUNCTIONAL DESCRIPTION (Continued)

Table 5. Typical Frequency vs. RC Values
V_{CC} = 5.0V @ 25°C

	Load Capacitor							
	33 pFd		56 pFd		100 pFd		0.00 1µFd	
Resistor (R)	A(Hz)	B(Hz)	A(Hz)	B(Hz)	A(Hz)	B(Hz)	A(Hz)	B(Hz)
1.0M	33K	31K	20K	20K	12K	11K	1.4K	1.4K
560K	56K	52K	34K	32K	20K	19K	2.5K	2.4K
220K	144K	130K	84K	78K	48K	45K	6K	6K
100K	315K	270K	182K	164K	100K	95K	12K	12K
56K	552K	480K	330K	300K	185K	170K	23K	22K
20K	1.4M	1M	884K	740K	500K	450K	65K	61K
10K	2.6M	2M	1.6M	1.3M	980K	820K	130K	123K
5K	4.4M	3M	2.8M	2M	1.7K	1.3M	245K	225K
2K	8M	5M	6M	4M	3.8K	2.7M	600K	536K
1K	12M	7M	8.8M	6M	6.3K	4.2M	1.0M	950K

Notes:
A = STD Mode Frequency.
B = Low EMI Mode Frequency.

Table 6. Typical Frequency vs. RC Values
V_{CC} = 3.3V @ 25°C

	Load Capacitor							
Resistor (R)	33 pFd		56 pFd		100 pFd		0.00 1µFd	
	A(Hz)	B(Hz)	A(Hz)	B(Hz)	A(Hz)	B(Hz)	A(Hz)	B(Hz)
1.0M	18K	18K	12K	12K	7.4K	7.7K	1K	1K
560K	30K	30K	20K	20K	12K	12K	1.6K	1.6K
220K	70K	70K	47K	47K	30K	30K	4K	4K
100K	150K	148K	97K	96K	60K	60K	8K	8K
56K	268K	250K	176K	170K	100K	100K	15K	15K
20K	690M	600K	463K	416K	286K	266K	40K	40K
10K	1.2M	1M	860K	730K	540K	480K	80K	76K
5K	2M	1.7M	1.5M	1.2M	950K	820K	151K	138K
2K	4.6M	3M	3.3M	2.4M	2.2M	1.6M	360K	316K
1K	7M	4.6M	5M	3.6M	3.6K	2.6M	660K	565K

Notes:
A = STD Mode Frequency.
B = Low EMI Mode Frequency.

FUNCTIONAL DESCRIPTION (Continued)

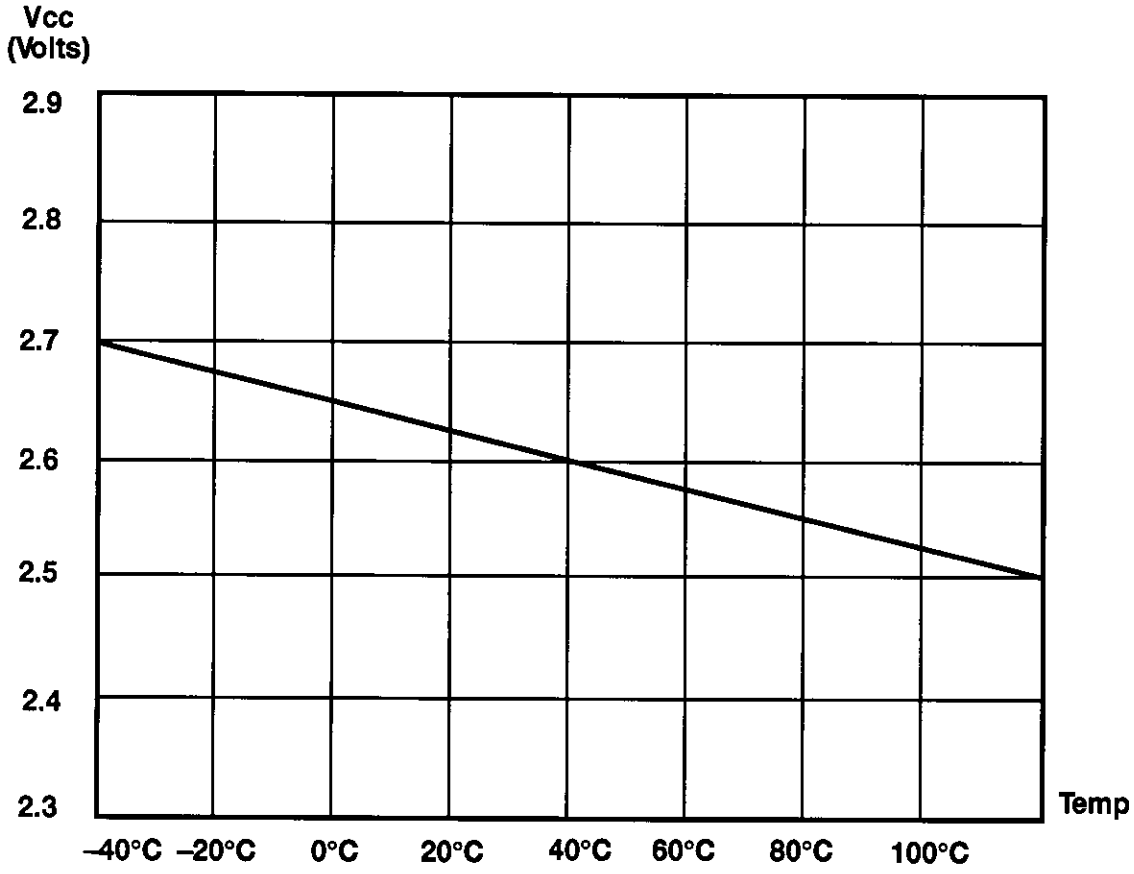


Figure 17. Typical Auto Reset Voltage (V_{LV}) vs. Temperature

Low EMI Emission

The Z8 can be programmed to operate in a low EMI Emission (Low Noise) Mode by means of an EPROM programmable bit option. Use of this feature results in:

- Less than 1 mA consumed during HALT Mode.
- All drivers slew rates reduced to 10 ns (typical).
- Internal SCLK/TCLK = XTAL operation limited to a maximum of 4 MHz–250 ns cycle time.
- Output drivers have resistances of 500 ohms (typical).
- Oscillator divide-by-two circuitry eliminated.

In addition to V_{DD} and GND (V_{SS}), the Z8 changes all its pin functions in the EPROM Mode. XTAL2 has no function, XTAL1 functions as $\overline{CE}$, P31 functions as $\overline{OE}$, P32 functions as EPM, P33 functions as V_{PP}, and P02 functions as $\overline{PGM}$.

ROM Protect. ROM Protect fully protects the Z8 ROM code from being read externally. When ROM Protect is selected, the instructions LDC and LDCI **are supported** (Z86E04/E08 and Z86C04/C08 do not support the instructions of LDE and LDEI). When the device is programmed for ROM Protect, the Low Noise feature will not automatically be enabled.

Please note that when using the device in a noisy environment, it is suggested that the voltages on the EPM and $\overline{CE}$ pins be clamped to V_{CC} through a diode to V_{CC} to prevent accidentally entering the OTP Mode. The V_{PP} requires both a diode and a 100 pF capacitor.

Auto Latch Disable. Auto Latch Disable option bit when programmed will globally disable all Auto Latches.

WDT Enable. The WDT Enable option bit, when programmed, will have the hardware enabled Permanent WDT enabled after exiting reset and can not be stopped in Halt or Stop Mode.

EPROM/Test Mode Disable. The EPROM/Test Mode Disable option bit, when programmed, will disable the EPROM Mode and the Factory Test Mode. Reading, verifying, and programming the Z8 will be disabled. To fully verify that this mode is disabled, the device must be power cycled.

User Modes. Table 7 shows the programming voltage of each mode.

Table 7. OTP Programming Table

Programming Modes	V_{PP}	EPM	$\overline{CE}$	$\overline{OE}$	$\overline{PGM}$	ADDR	DATA	V_{CC}*
EPROM READ	NU	V_H	V_{IL}	V_{IL}	V_{IH}	ADDR	Out	5.0V
PROGRAM	V_H	V_{IH}	V_{IL}	V_{IH}	V_{IL}	ADDR	In	6.4V
PROGRAM VERIFY	V_H	V_{IH}	V_{IL}	V_{IL}	V_{IH}	ADDR	Out	6.4V
EPROM PROTECT	V_H	V_H	V_H	V_{IH}	V_{IL}	NU	NU	6.4V
LOW NOISE SELECT	V_H	V_{IH}	V_H	V_{IH}	V_{IL}	NU	NU	6.4V
AUTO LATCH DISABLE	V_H	V_{IH}	V_H	V_{IL}	V_{IL}	NU	NU	6.4V
WDT ENABLE	V_H	V_{IL}	V_H	V_{IH}	V_{IL}	NU	NU	6.4V
EPROM/TEST MODE	V_H	V_{IL}	V_H	V_{IL}	V_{IL}	NU	NU	6.4V

Notes:

1. V_H =12.75V ± 0.25 V_{DC} .
2. V_{IH} = As per specific Z8 DC specification.
3. V_{IL} = As per specific Z8 DC specification.
4. X = Not used, but must be set to V_H or V_{IH} level.
5. NU = Not used, but must be set to either V_{IH} or V_{IL} level.
6. I_{PP} during programming = 40 mA maximum.
7. I_{CC} during programming, verify, or read = 40 mA maximum.
8. * V_{CC} has a tolerance of ±0.25V.

FUNCTIONAL DESCRIPTION (Continued)

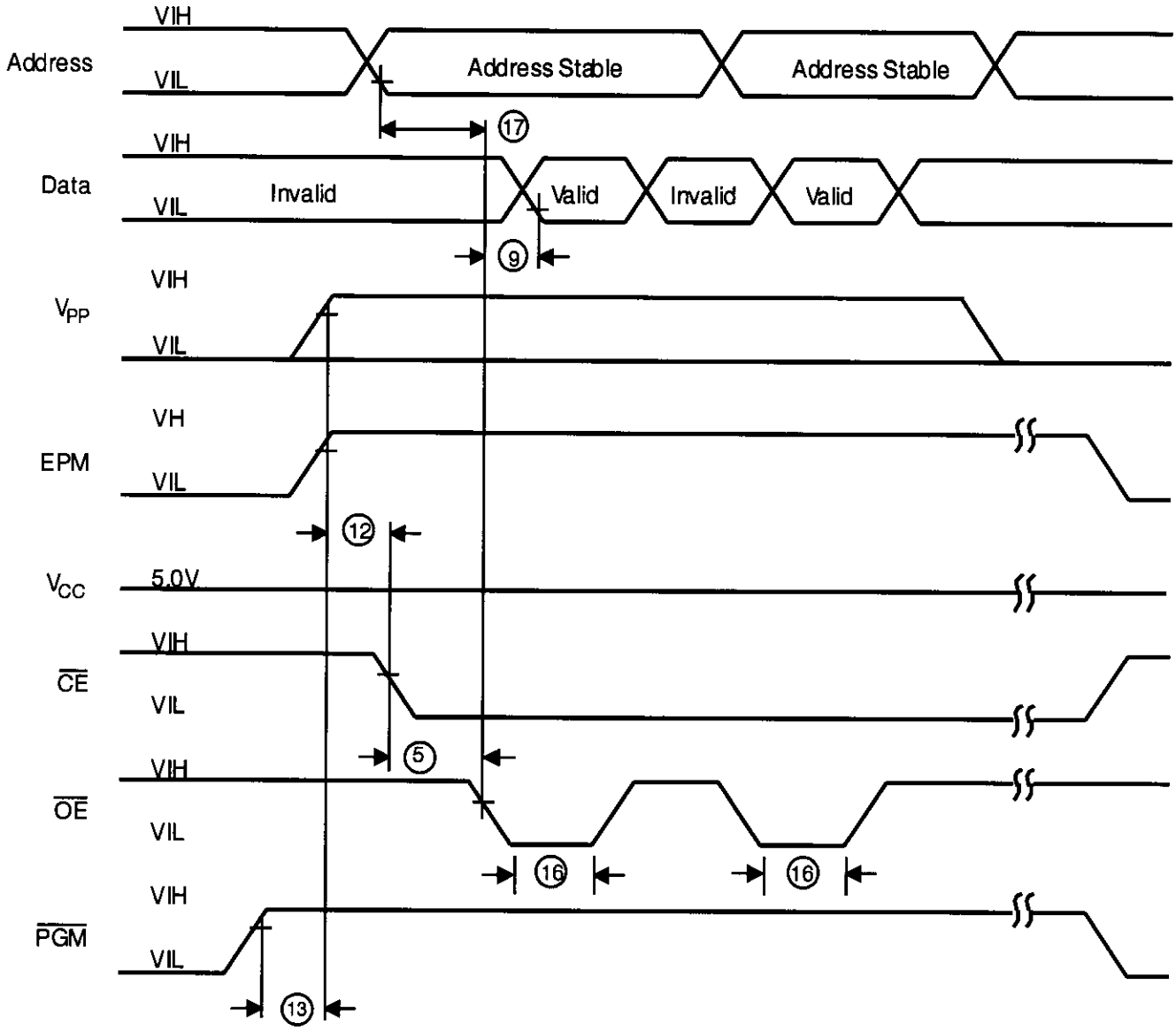


Figure 19. Z86E04/E08 Programming Waveform (EPROM Read)

FUNCTIONAL DESCRIPTION (Continued)

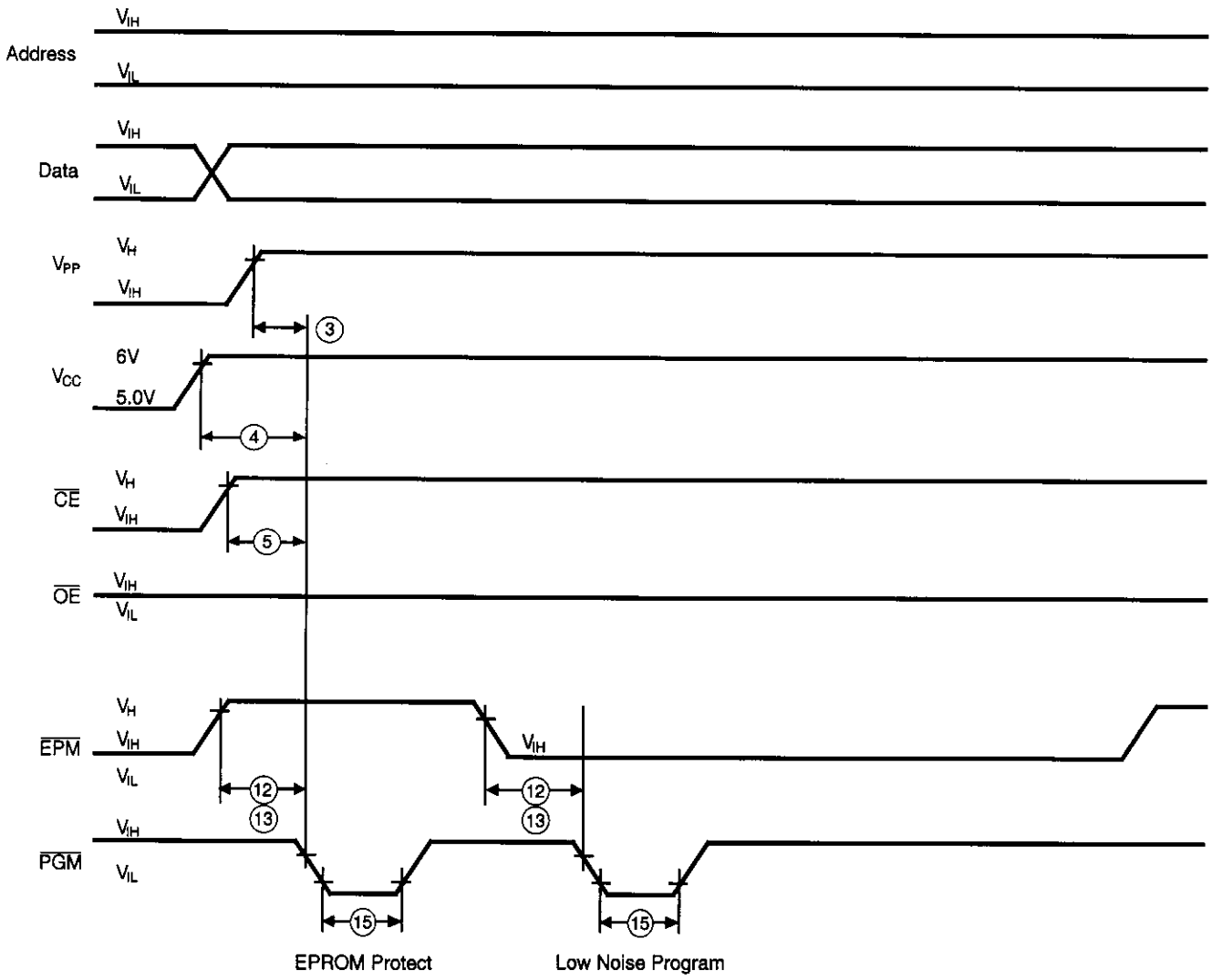


Figure 21. Z86E04/E08 Programming Options Waveform (EPROM Protect and Low Noise Program)

Z8 CONTROL REGISTERS (Continued)

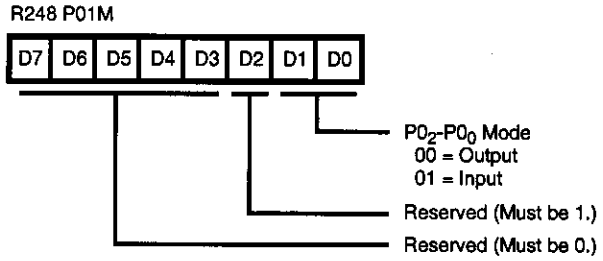


Figure 31. Port 0 and 1 Mode Register ($F8_H$: Write Only)

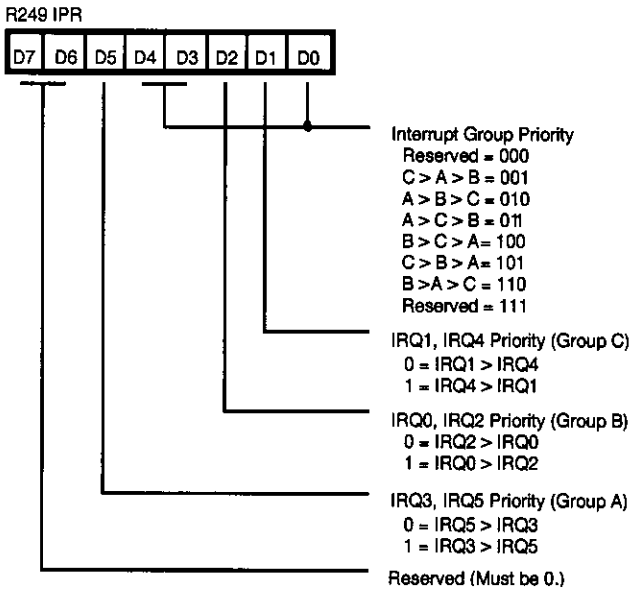


Figure 32. Interrupt Priority Register ($F9_H$: Write Only)

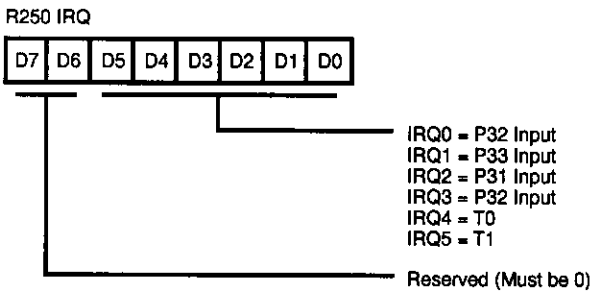


Figure 33. Interrupt Request Register (FA_H: Read/Write)

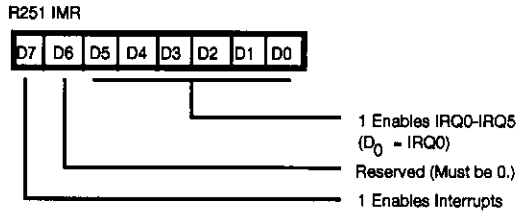


Figure 34. Interrupt Mask Register (FB_H: Read/Write)

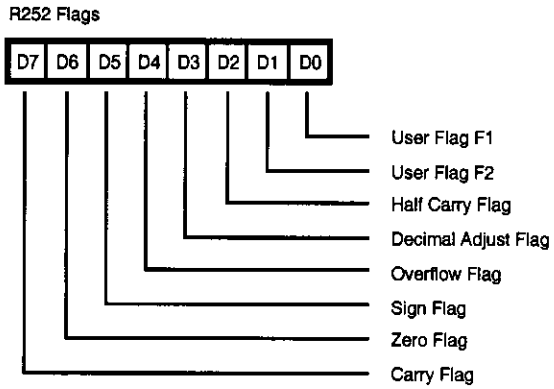


Figure 35. Flag Register (FC_H: Read/Write)

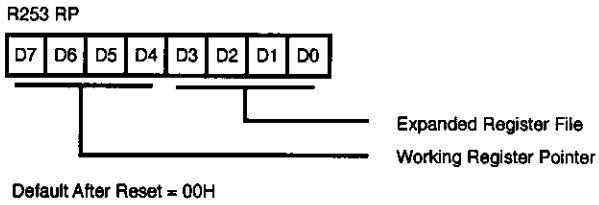


Figure 36. Register Pointer (FD_H: Read/Write)

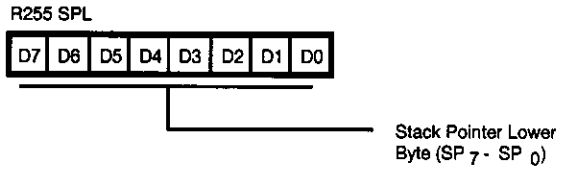
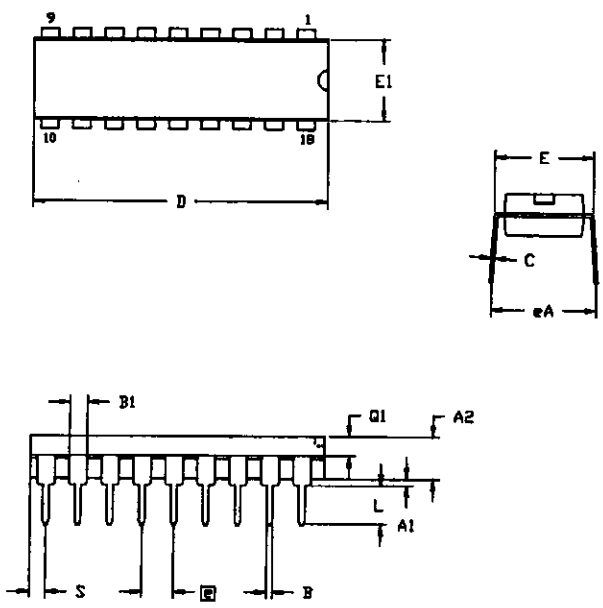


Figure 37. Stack Pointer (FF_H: Read/Write)

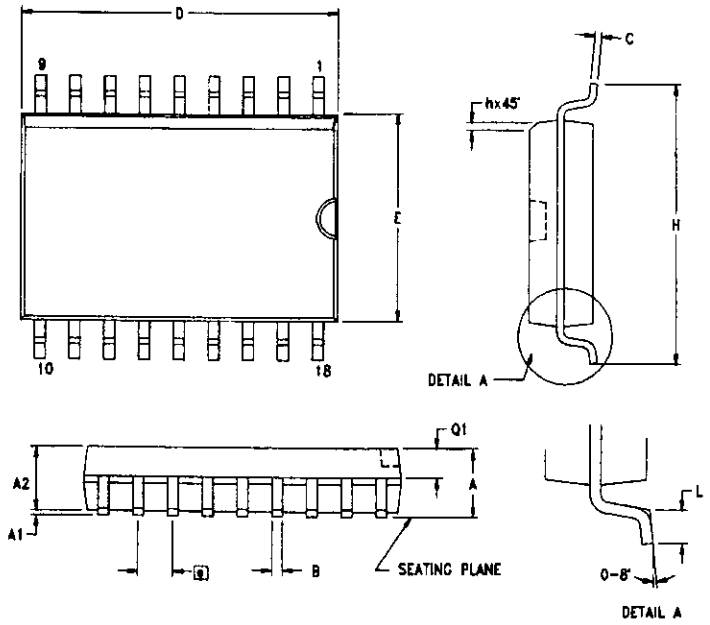
PACKAGE INFORMATION



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.51	0.81	.020	.032
A2	3.25	3.43	.128	.135
B	0.38	0.53	.015	.021
B1	1.14	1.65	.045	.065
C	0.23	0.38	.009	.015
D	22.35	23.37	.880	.920
E	7.62	8.13	.300	.320
E1	6.22	6.48	.245	.255
e	2.54 TYP		.100 TYP	
eA	7.87	8.89	.310	.350
L	3.18	3.81	.125	.150
Q1	1.52	1.65	.060	.065
S	0.89	1.65	.035	.065

CONTROLLING DIMENSIONS : INCH

18-Pin DIP Package Diagram



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	2.40	2.65	0.094	0.104
A1	0.10	0.30	0.004	0.012
A2	2.24	2.44	0.088	0.096
B	0.36	0.46	0.014	0.018
C	0.23	0.30	0.009	0.012
D	11.40	11.75	0.449	0.463
E	7.40	7.60	0.291	0.299
e	1.27 TYP		0.050 TYP	
H	10.00	10.65	0.394	0.419
h	0.30	0.50	0.012	0.020
L	0.60	1.00	0.024	0.039
Q1	0.97	1.07	0.038	0.042

CONTROLLING DIMENSIONS : MM
LEADS ARE COPLANAR WITHIN .004 INCH.

18-Pin SOIC Package Diagram